

**DESCRIPTION**

The SE10F15B24A is a low capacitance transient voltage suppressor array, designed to protect applications such as Cell Phone Handsets and Accessories. This product is rated at 150 Watts for an 8/20µs waveform.

The SE10F15B24A meets IEC 61000-4-2 (ESD) and IEC 61000-4-4 (EFT) requirements. At higher operating frequencies or faster edge rates, insertion loss and signal integrity are a major concern. The SE10F15B24A offers a low capacitance and low leakage current in a miniature DFN 1006D N package.

**FEATURES**

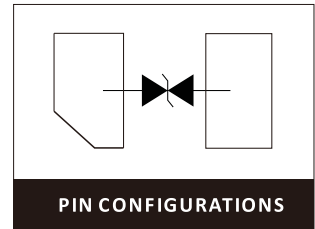
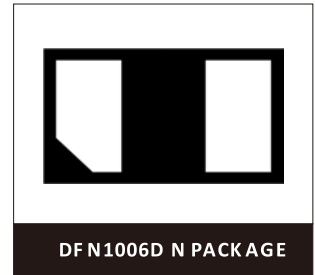
- >150 Watts Peak Pulse Power per Line (tp=8/20 µs)
- >Protects One Power or I/O Port
- >Low clamping voltage
- >Low leakage current

**APPLICATIONS**

- >Cell Phone Handsets and Accessories
- >Microprocessor based equipment
- >Personal Digital Assistants (PDA's)
- >Notebooks, Desktops, and Servers
- >Peripherals
- >Pagers

**IEC COMPATIBILITY**

- >IEC61000-4-2 (ESD) ±25 kV (Air), ± 15kV (Contact) : 24V
- >IEC61000-4-4 (EFT) 40A (5/50ns)
- >IEC61000-4-5 (LIGHTNING) 3A (8/20µs)



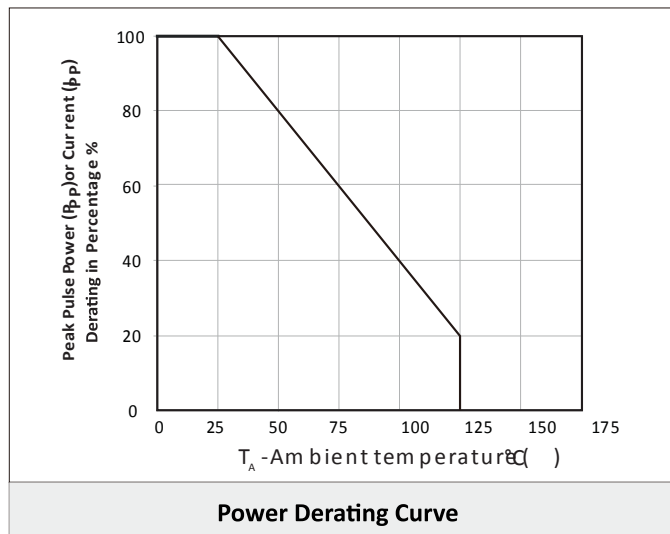
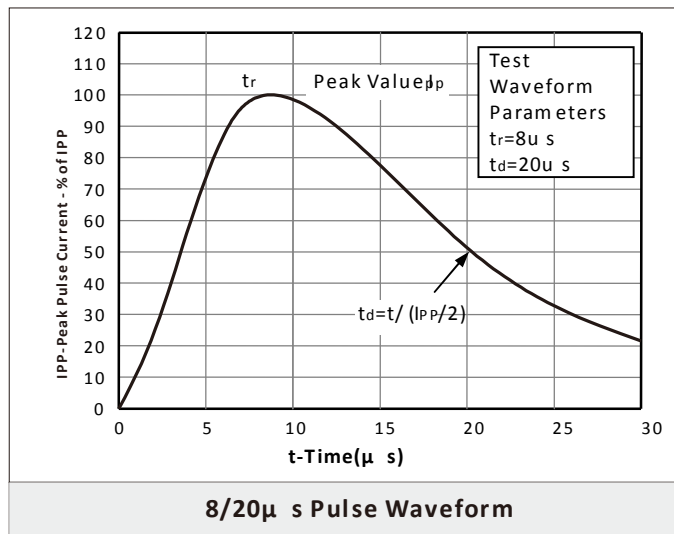
**MAXIMUM RATINGS @ 25°C UNLESS OTHERWISE SPECIFIED**

PARAMETER	SYMBOL	VALUE	UNIT
Peak Pulse Power (tp=8/20µs waveform)	PPP	150	Watts
Lead Soldering Temperature	TL	260(10 sec.)	°C
Operating Temperature Range	TJ	-40~125	°C
Storage Temperature Range	TSTG	-55~150	°C

**ELECTRICAL CHARACTERISTICS PER LINE @ 25°C UNLESS OTHERWISE SPECIFIED**

PART NUMBER	DEVICE MARKING	VRWM	Vb	IT	Vc		IR	CT
		(V) Max.	(V) Min.	(mA)	Max.	@A	(µA) Max.	(pF) Typ.
SE10F15B24A	DH	24	26.7	1	55	3	1	24

**CHARACTERISTIC CURVES**

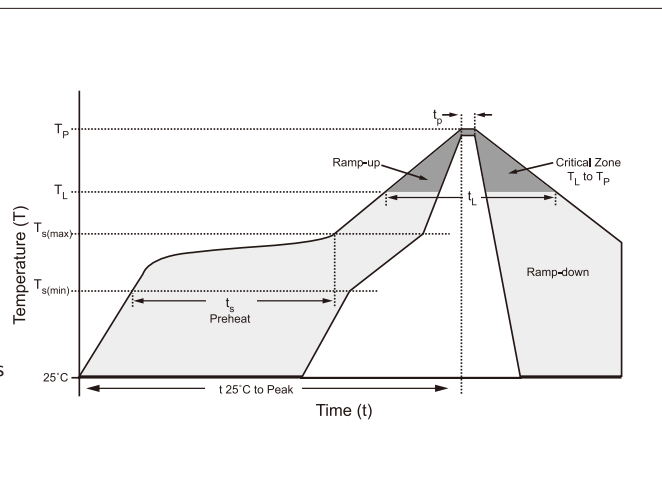


**ENVIRONMENTAL CHARACTERISTICS**

Testing Items	Technical Standards
High Temperature Reverse Bias Test	Temperature:150 ± 3°C; Bias=80% VDRM; Time:168 H
High Temperature Life Test	Temperature:150°C; Time:168 H
High-Low Temperature Cycle Test	Temperature:From -40 to 150°C; Dwell Time:30min, 10-100 Cycles
High Temperature & High Humidity Test	Temperature:85°C; Humidity:85%; Time:168 H
Pressure Cooker Test	Temperature:121°C, 2atm. Humidity:100%; Time:24 H To 168 H
Resistance Of Soldering Heat	Temperature:260±5°C; Time Of Dip Soldering: 10s, 3 Times

**REFLOW PROFILE**

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min (Ts(min))	150° C
	Temperature Max (Ts(max))	200° C
	Time (min to max) (ts)	60 – 180 secs
Average ramp up rate (Liquidus Temp (TL) to peak)		3° C /second max
Ts(max) to TL - Ramp-up Rate		3° C /second max
Reflow	Temperature (Ti) (Liquidus)	217° C
	Time (min to max) (ts)	60 – 150 seconds
Peak Temperature (Tp)		260° C
Time within 5° C of actual peak Temperature (tp)		20 – 40 seconds
Ramp-down Rate		6° C /second max
Time 25° C to peak Temperature (T)		8 minutes Max.
Do not exceed		260° C



**DFN1006DN PACKAGE DIMENSIONS**

OUTLINEDIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.45	0.55	0.018	0.022
A1	0	0.05	0	0.002
b	0.45	0.55	0.018	0.022
c	0.12	0.18	0.005	0.007
D	0.95	1.05	0.037	0.041
e	0.65BSC		0.026BSC	
E	0.55	0.65	0.022	0.026
L	0.20	0.30	0.008	0.012
L1	0.05REF		0.002REF	
h	0.07	0.17	0.003	0.007

**RECOMMENDED PAD LAYOUT DIMENSIONS**

DIM	MILLIMETERS	INCHES
A	1.20	3.12
B	0.47	0.91
C	0.60	0.91

**ORDERING INFORMATION**

Part Number	Component Package	QTY/Reel	Reel Size
SE10F15B24A	DFN1006DN	10000PCS	7"

## **CONTACT US**

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